## intel foundry

# Al Inspired. Systems Accelerated.

Kevin O'Buckley Senior Vice President, Intel Foundry







## **Perfect Storm Reshaping the** Semiconductor Industry

### **Rising Costs**



### Exponential Growth



1.7x YoY AI Chips Volume Growth

### Supply Chain Challenges





intel foundry

### 6.3 TWh Annual Power Consumption of AI Server Chips

## Structural Shifts In Customer Needs

AI / HPC Has Surpassed Mobile Revenue



Systems of Chips Chiplets Surpass Monolithic by 2028

ource: IHS, SemiAnal

Source: Gartne



### **Vertical Integration** ≤5nm Wafer TAM: 4% in 2024 to 12% in 2030



## Challenge: **Power Growing Unsustainably**

Al Chips Consume More Power Than 61% of Countries



### Systems Consume **3x Power of UK** Data Center Energy Consumption, TWh

Data Center Energy Consumption, TWh

### 16% CAGR

**Data Center Energy Use High Case** orecast

Data Center Energy Use Actual

2022

2026

## Challenge: Mismatch in Scaling

Scaling of Peak Hardware FLOPS and Memory/Interconnect Bandwidth



HW FLOPS 60,000x/20 yrs. (3.0x/2yrs)

DRAM BW 100x/20 yrs. (1.6x/2yrs)

Interconnect BW 30x/20 yrs. (1.4x/2yrs)

2023

## Challenge: Mismatch In Scaling



intel foundry

### HW FLOPS (required): ~60,000x / 20yrs

Up to 30x GAP! = brute force (high cost, power) Needed to scale AI

=Inefficient systems

2032 2033

# The Path Forward



## Systematic Path to Exponential Improvement

### System Revolution

System Evolution

System Technology Co-Optimization Reduced precision numbers New memories & network topologies Model efficiency

Evolve standards e.g. serial HBM, AIC Moore's law + packaging

Hardware optimized for software Memory, compute, networking in harmony

Time



## Must Optimize From Factory Network **Through Software**

2024 Software & services (direct and thru eco-system) AI NIC / chiplet New technologies Network **Photonics** PCIe, UCIe, SerDes / Ethernet evolution Interconnect Evolve HBM, AI base die New technologies Memory Immersion >2000w TDP Cooling > 1300W TDP Substrate Larger size w/ embeddings **Glass substrate** EMIB-8HBM EMIB 12HBM EMIB >12HBM Package Foveros 3D Direct 9um Foveros 3D Direct 3um Next 18A w. 1st PowerVia 14A w. 1st High-NA Next Process

Systems Solutions

### intel foundry

All product plans and roadmaps are subject to change without notice





## Sustainable Systems Innovations for Al's Next Frontier

### Turning a Corner



### **Truly Differentiated**





intel foundry

### Results

## Notices and Disclaimers



For complete notices and disclaimers, visit www.intel.com/PerformanceIndex or scan the QR code:

Learn more at <u>www.Intel.com/ProcessInnovation</u>.

All product and service plans, and roadmaps are subject to change without notice

Statements in this document that refer to future plans or expectations are forward-looking statements. These statements are based on current expectations and involve many risks and uncertainties that could cause actual results to differ materially from those expressed or implied in such statements. For more information on the factors that could cause actual results to differ materially, see our most recent earnings releases, annual report on form 10-K and other SEC filings at <u>www.intc.com</u>.

Intel does not control or audit third party data. You should consult other sources to evaluate accuracy.

Intel is committed to the continued development of more sustainable products, processes, and supply chain as we strive to prioritize greenhouse gas reduction and improve our global environmental impact. Where applicable, environmental attributes of a product family or specific SKU will be stated with specificity. Refer to the 2022 Corporate Responsibility Report for further information."

© Intel Corporation. Intel, the Intel logo, and other Intel marks are trademarks of Intel Corporation or its subsidiaries. Other names and brands may be claimed as the property of others.

# **intelfoundry** We were made for this